



## Product Data Sheet

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**PRODUCT #: N5111**

# **CIRCUTEK CC-710**

Alkaline Cleaner/Conditioner

**DESCRIPTION:** An alkaline solution to prepare and condition printed circuit boards for through-hole metallization. **CIRCUTEK CC-710** is specially formulated to remove fingerprints, light soil and other contaminants from copper foil. It also conditions hard to catalyze surfaces such as organic resin and glass for subsequent electroless copper deposition. **CIRCUTEK CC-710** is supplied as a liquid concentrate.

**BENEFITS:**

- **Combines cleaning with conditioning of the resin surface**
- **Effective cleaning with clean rinsing characteristics**

**EQUIPMENT:**

Tanks should be constructed of polypropylene, high temperature PVC or stainless steel. Heaters should be constructed of Teflon<sup>®</sup>, stainless steel or titanium.

**MAKE-UP/  
OPERATING  
INSTRUCTIONS:**

- CIRCUTEK CC-710:** 5% by volume
- Deionized Water:** 95%
- Temperature:** 130 - 150°F
- Immersion Time:** 3 - 6 minutes
- Agitation:** Work bar agitation

**Procedure:**

1. Fill tank ¾ full with deionized water.
2. Add the required amount of **CIRCUTEK CC-710** and mix well.
3. Adjust to final volume with deionized water and mix well.

**CONTROL  
PARAMETERS:**

To achieve optimum results, the bath should be maintained at the following concentration

<u><b>CIRCUTEK CC-710 Cleaner/Conditioner</b></u>	<b>OPTIMUM</b>	<b>RANGE</b>
<b>CIRCUTEK CC-710 Concentration:</b>	5%	3.5-5%

**NOTE :** The desmear and electroless copper deposition process is laminate specific. Parameters specified in RBP supplied operating guides for particular installations always supersede the parameters listed above.

